

NCE N-Channel Super Trench Power MOSFET

Description

The NCEP6035AQU uses **Super Trench** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of $R_{DS(ON)}$ and Q_g . This device is ideal for high-frequency switching and synchronous rectification.

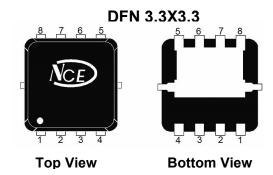
Application

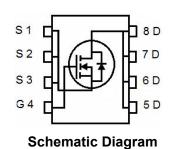
- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

General Features

- V_{DS} =60V, I_D =35A $R_{DS(ON)}$ =10.0m Ω (typical) @ V_{GS} =10V $R_{DS(ON)}$ =13.0m Ω (typical) @ V_{GS} =4.5V
- Excellent gate charge x R_{DS(on)} product(FOM)
- Very low on-resistance R_{DS(on)}
- 150 °C operating temperature
- Pb-free lead plating

100% UIS TESTED! 100% ΔVds TESTED!





Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCEP6035AQU	NCEP6035AQU	DFN3.3X3.3-8L	-	-	-

Absolute Maximum Ratings (T_c=25℃unless otherwise noted)

Parar	neter	Symbol	Limit	Unit
Drain-Source Voltage		VDS	60	V
Gate-Source Voltage		Vgs	±20	V
Drain Current-Continuous		I _D	35	Α
Drain Current-Continuous(T _C =100	℃)	I _D (100℃)	27	Α
Pulsed Drain Current		I _{DM}	160	Α
Maximum Power Dissipation		P _D	41	W
Derating factor			0.33	W/℃
Single pulse avalanche energy (Not	e 5)	E _{AS}	96	mJ
V _{DS} Spike (Note 6)	10µs	72		V
Operating Junction and Storage Temperature Range		T_{J}, T_{STG}	-55 To 150	$^{\circ}$

Thermal Characteristic

Thermal Resistance,Junction-to-Case ^(Note 2)	Rejc	3.05	°C/W
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NCEP6035AQU

Electrical Characteristics (T_C=25°Cunless otherwise noted)

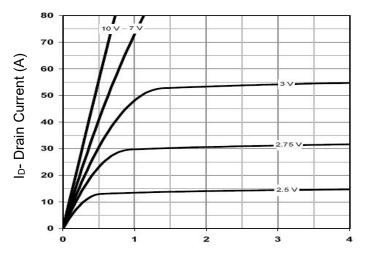
Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250µA	60		-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =60V,V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS}$, $I_{D}=250\mu A$	1.2	1.7	2.4	V
Dunin Course On State Besietenes	Б	V _{GS} =10V, I _D =20A	-	10	12	mΩ
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =4.5V, I _D =20A	-	13	15	
Forward Transconductance	g FS	V _{DS} =5V,I _D =20A		60	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C _{lss}	V 20V/V 0V	-	1010	-	PF
Output Capacitance	Coss	$V_{DS}=30V, V_{GS}=0V,$	-	183.2	-	PF
Reverse Transfer Capacitance	Crss	F=1.0MHz	-	9.9	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t _{d(on)}		-	4.3	-	nS
Turn-on Rise Time	t _r	V_{DD} =30 V , I_D =20 A	-	2.7	-	nS
Turn-Off Delay Time	t _{d(off)}	V_{GS} =10 V , R_{G} =1.6 Ω	-	13.8	-	nS
Turn-Off Fall Time	t _f		-	2.7	-	nS
Total Gate Charge	Qg	.,	-	21.8	-	nC
Gate-Source Charge	Q _{gs}	$V_{DS}=30V,I_{D}=20A,$	-	4.6		nC
Gate-Drain Charge	Q_{gd}	V _{GS} =10V	-	3.5		nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =20A	-		1.2	V
Diode Forward Current (Note 2)	Is		-	-	35	Α
Reverse Recovery Time	t _{rr}	T _J = 25°C, I _F =20A	-	18	-	nS
Reverse Recovery Charge	Qrr	$di/dt = 100A/\mu s^{(Note3)}$	-	12	-	nC

Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, $t \le 10$ sec.
- 3. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.
- 4. Guaranteed by design, not subject to production
- 5. EAS condition : Tj=25 $^{\circ}\text{C}$,VDD=30V,VG=10V,L=0.5mH,Rg=25 Ω
- 6. The spike duty cycle 5% max, limited by junction temperature $T_{J}(\mbox{MAX})\mbox{=}125^{\circ}~$ C.

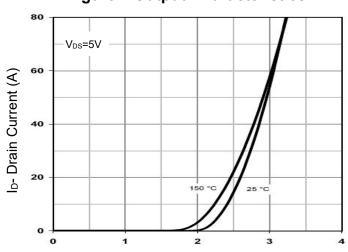


Typical Electrical and Thermal Characteristics



Vds Drain-Source Voltage (V)

Figure 1 Output Characteristics



Vgs Gate-Source Voltage (V)

Figure 2 Transfer Characteristics

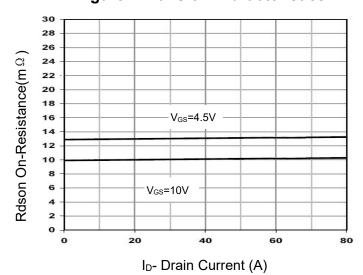
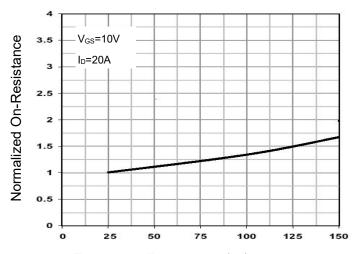
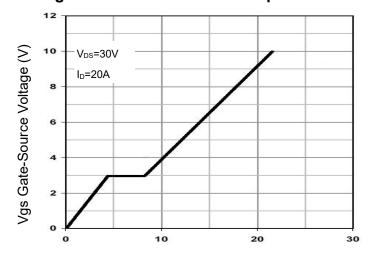


Figure 3 Rdson- Drain Current



T_J-Junction Temperature(°C)

Figure 4 Rdson-Junction Temperature



Qg Gate Charge (nC)
Figure 5 Gate Charge

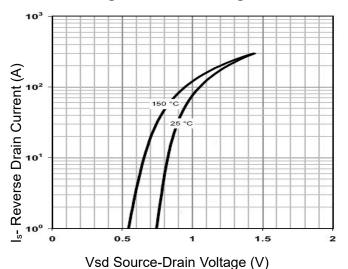
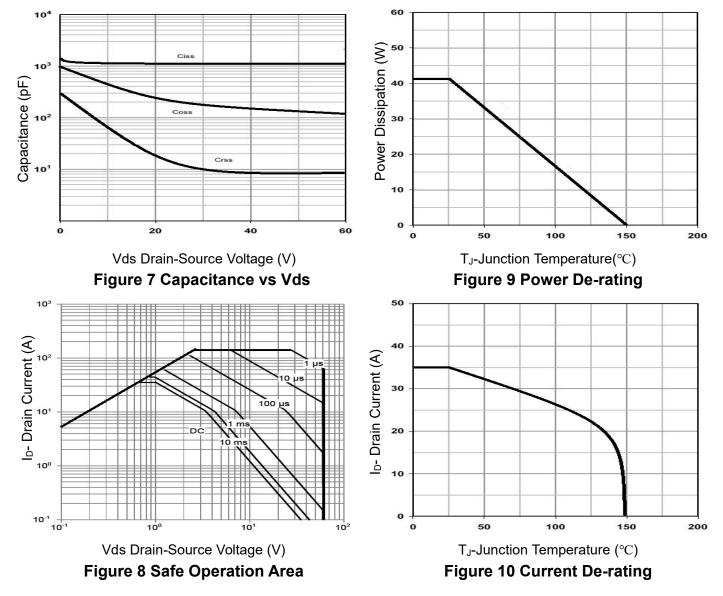


Figure 6 Source- Drain Diode Forward





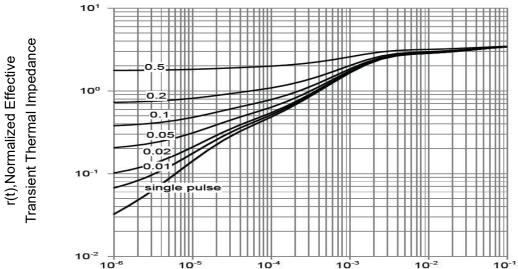
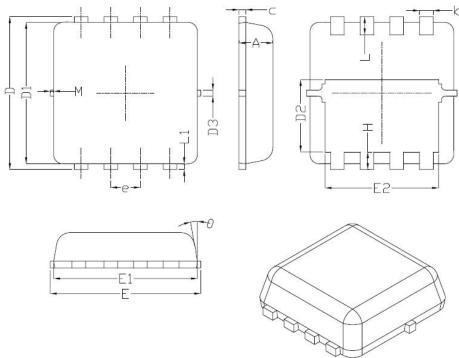


Figure 11 Normalized Maximum Transient Thermal Impedance

Square Wave Pluse Duration(sec)

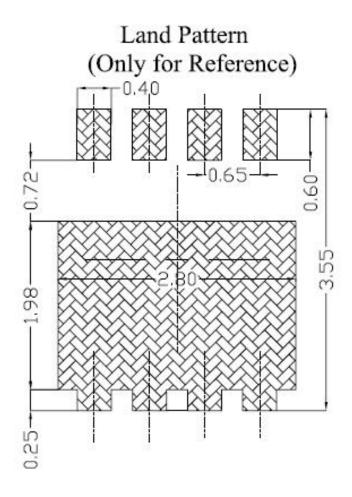


DFN3.3X3.3-8L Package Information



Cumb al	Dimensions In Millimeters				
Symbol	Min.	Nom.	Max.		
A	0.70	0.75	0.80		
b	0.25	0.30	0.35		
С	0.10	0.15	0.25		
D	3.25	3.35	3.45		
D1	3.00	3.10	3.20		
D2	1.78	1.88	1.98		
D3	-	0.13	-		
E	3.10	3.20	3.30		
E1	3.00	3.15	3.20		
E2	2.39	2.49	2.59		
е		0.65BSC			
Н	0.30	0.39	0.50		
L	0.30	0.40	0.50		
L1	-	0.13	-		
М	*	*	0.15		
θ		10°	12 [°]		





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NCEP6035AQU

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